# Refine Search

io/156,378

#### Search Results -

Terms	Documents	
L7 and equation	3	

US Pre-Grant Publication Full-Text Database US Patents Full-Text Database

Database:

US OCR Full-Text Database EPO Abstracts Database JPO Abstracts Database Derwent World Patents Index IBM Technical Disclosure Bulletins

Search:

L8

Refine Search

Recall Text 🗲 Clear Interrupt

#### Search History

18

<u>L3</u>

DATE: Saturday, June 26, 2004 Printable Copy Create Case

Set Nam		Hit Count Set Name result set		
DB=U	SPT; PLUR=YES; OP=ADJ	•		
<u>L8</u>	L7 and equation	3	1.8	
<u>1.7</u>	L3 and oxidation	6	<u>L7</u>	
<u>L6</u>	L5 and plasma	. 3	<u>L6</u>	
<u>L.5</u>	L3 and (atomic near2 percent)	√ 4	<u>L5</u>	
<u>1.4</u>	L3 and (argon adj plasma)	2	· · <u>1.4</u>	

L2 and magnesium L1 and (copper adj alloy) <u>L2</u> . 154 1.2 (thin adj film) near2 transistor 14127 L1LI

END OF SEARCH HISTORY

<u>L3</u>

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		000000000000000000000000000000000000000	ate OACS		

### Search Results - Record(s) 1 through 3 of 3 returned.

1. Document ID: US 6686661 B1

L8: Entry 1 of 3

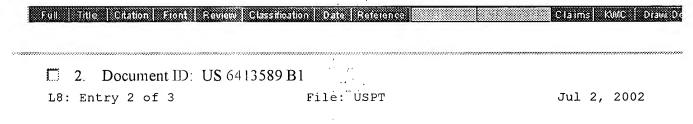
File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6686661 B1

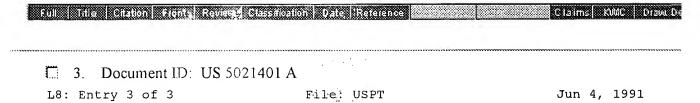
TITLE: Thin film transistor having a copper alloy wire



US-PAT-NO: 6413589

DOCUMENT-IDENTIFIER: US 6413589 B1

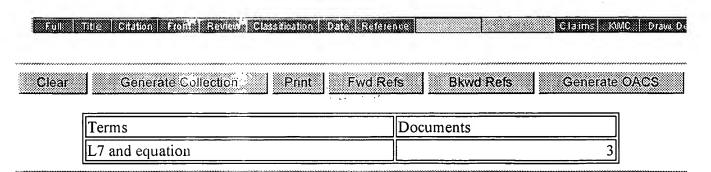
TITLE: Ceramic coating method



US-PAT-NO: 5021401

DOCUMENT-IDENTIFIER: US 5021401 A

TITLE: Integrated production of superconductor insulation for chemical vapor deposition of nickel carbonyl



Display Format: TI Change Format

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Clear Generale Collection Print Fwd Refs Bkwd Refs
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Search Results - Record(s) 1 through 6 of 6 returned.

1. Document ID: US 6743716 B2

L7: Entry 1 of 6

File: USPT

Jun 1, 2004

US-PAT-NO: 6743716

DOCUMENT-IDENTIFIER: US 6743716 B2

TITLE: Structures and methods to enhance copper metallization

Full Title: Challon, Front, Review, Classification, Date Reterence Claims (WIC) Draw, Dr

2. Document ID: US 6686661 B1

L7: Entry 2 of 6

File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6686661 B1

TITLE: Thin film transistor having a copper alloy wire

Full Title Citation From Process Classification Date Reference Communication Districts

3. Document ID: US 6420262 B1

L7: Entry 3 of 6

File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 6420362 B1

TITLE: Structures and method: to enhance copper metallization

Full Title Gilation F/G 1975 KSUssation(in Dale) Science Claims KWC Draw Dr

4. Document ID: US 6413589 B1

L7: Entry 4 of 6

File: USPT

Jul 2, 2002

US-PAT-NO: 6413589

DOCUMENT-IDENTIFIER: US 6413539 B1

TITLE: Ceramic coating method

Full Title Citation Front Review	Signassification   Date   Reference	Claims KMC Draw
F. 5 D TD. 110.5	COALDA A	
5. Document ID: US 5.	094184 A File: USPT	Dec 2, 1997
S-PAT-NO: 5694184 CUMENT-IDENTIFIER: US 5694	184 A	·
TLE: Liquid crystal displa	y device	
Full Title Challon Front Esc.	GCISSSIfication   Date   Reference	Claims KMC Drav
☐ 6. Document ID: US 5.	021401 A	
L7: Entry 6 of 6	File: USPT	Jun 4, 1991
S-PAT-NO: 5021401 DCUMENT-IDENTIFIER: US 5021	401 A	
TLE: Integrated production position of nickel carbony	of superconductor insulation l	for chemical vapor
Ful Title Citation Ficht. Selice	. Coessification Date Reference	CEIME KOC DE
Clear Generate Collinction	Print Fwd Refs Bkv	vd Refs Generate OACS
Terms	Document	r.s.

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Generate OACS

Search Results - Record(s) 1 through 4 of 4 returned.

1. **Document ID**: US 6743716 B2

L5: Entry 1 of 4

File: USPT

Jun 1, 2004

US-PAT-NO: 6743716

DOCUMENT-IDENTIFIER: US 6743716 B2

TITLE: Structures and methods to enhance copper metallization

Full Title Chation Front 7707 Cessitivation Date Reference Claims KWC Draw De

2. Document ID: US 6686661 B1

L5: Entry 2 of 4

File: USPT

Feb 3, 2004

US-PAT-NO: 6686661

DOCUMENT-IDENTIFIER: US 6836561 B1

TITLE: Thin film transision having a copper alloy wire

Full Title Challes Fig. Sessification Cate Reference Claims DMC Draw De

3. Document ID: US 6541858 B1

L5: Entry 3 of 4

File: USPT

Apr 1, 2003

US-PAT-NO: 6541858

DOCUMENT-IDENTIFIER: US 6541858 B1

TITLE: Interconnect allog and methods and apparatus using same

Full Title Gibilion Fp. Called Callon Date Reference Claims KWC Draw Du

4. Document ID: US 6400262 B1

L5: Entry 4 of 4

File: USPT

Jul 16, 2002

US-PAT-NO: 6420262

DOCUMENT-IDENTIFIER: US 642 262 B1

TITLE: Structures and methods to enhance copper metallization

Full   Title   Citation   From   NOV.   Classification   Date	References Claims KMC Draw Dr
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Terms	Documents
L3 and (atomic near2 1 reent)	4

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			ate OACS		

Search Results - Record(s) 1 through 2 of 2 returned.

☐ 1. Document 10: US 0.05878 B1

L4: Entry 1 of 2

File: USPT

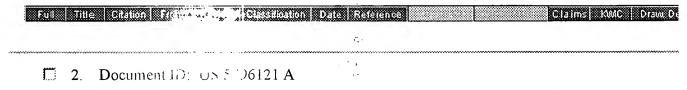
Dec 17, 2002

US-PAT-NO: 6495878

DOCUMENT-IDENTIFIER: US C192.78 B1

TITLE: Interlayer oxide work aming thin films for high dielectric constant

application



L4: Entry 2 of 2

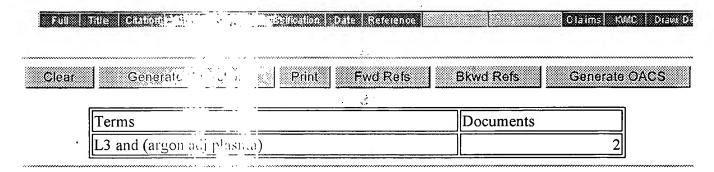
File: USPT

Aug 18, 1998

US-PAT-NO: 5796121

DOCUMENT-IDENTIFIER: US 5 5 21 A

TITLE: Thin film traps of a fabricated on plastic substrates



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